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**(54) Title (EN):** LIGHT-EMITTING DEVICE PACKAGE

**(54) Title (FR):** BOÎTIER DE DISPOSITIF ÉLECTROLUMINESCENT

**(54) Title (KO):** 발광 소자 패키지

**(57) Abstract:**

**(EN):** The present invention provides a light-emitting device package comprising: a light-emitting diode device for providing light of a wavelength in a predetermined region; a circuit board disposed at the lower surface of the light-emitting diode device so as to be electrically connected to the light-emitting diode device; a first phosphor layer formed in a cap shape so as to be disposed to encompass the side surfaces and the upper surface of the light-emitting diode device, and formed such that the thickness of a side part and the thickness of an upper part are uniform; and a second phosphor layer formed in a cap shape so as to be disposed to encompass the side surfaces and the upper surface of the first phosphor layer, and formed such that the thickness of a side part and the thickness of an upper part are uniform.

**(FR):** La présente invention concerne un boîtier de dispositif électroluminescent comportant: un dispositif à diode électroluminescente servant à fournir une lumière d'un longueur d'onde située dans une région prédéterminée; une carte à circuits disposée au niveau de la surface inférieure du dispositif à diode électroluminescente de façon à être reliée électriquement au dispositif à diode électroluminescente; une première couche de luminophore réalisée en forme de calotte de façon à être disposée pour englober les surfaces latérales et la surface supérieure du dispositif à diode électroluminescente, et formée de telle façon que l'épaisseur d'une partie latérale et l'épaisseur d'une partie supérieure soient uniformes; et une deuxième couche de luminophore réalisée en forme de calotte de façon à être disposée pour englober les surfaces latérales et la surface supérieure de la première couche de luminophore, et formée de telle façon que l'épaisseur d'une partie latérale et l'épaisseur d'une partie supérieure soient uniformes.

**(KO):** 본 발명은 소정 영역의 파장의 빛을 제공하는 발광 다이오드 소자, 상기 발광 다이오드 소자의 하면에 배치되어 상기 발광 다이오드 소자와 전기적으로 연결되는 회로 기판, 상기 발광 다이오드 소자의 측면과 상면을 둘러싸며 배치되도록 캡(cap) 형상으로 형성되며, 측부의 두께 및 상부의 두께가 균일하게 형성된 제 1 형광체층 및 상기 제 1 형광체층의

측면과 상면을 둘러싸며 배치되도록 캡 형상으로 형성되며, 측부의 두께 및 상부의 두께가 균일하게 형성된 제 2 형광체 층을 포함하는 발광 소자 패키지를 제공한다.

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